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16-Kbit I²C Serial EEPROM, Industrial Grade

AT24C16C

Features

- Low-Voltage Operation:
  - V_{CC} = 1.7V to 5.5V
- Internally Organized as 2,048 x 8 (16K)
- Industrial Temperature Range: -40°C to +85°C
- I²C-Compatible (Two-Wire) Serial Interface:
  - 100 kHz Standard Mode, 1.7V to 5.5V
  - 400 kHz Fast Mode, 1.7V to 5.5V
  - 1 MHz Fast Mode Plus (FM+), 2.5V to 5.5V
- Schmitt Triggers, Filtered Inputs for Noise Suppression
- Bidirectional Data Transfer Protocol
- Write-Protect Pin for Full Array Hardware Data Protection
- Ultra Low Active Current (3 mA maximum) and Standby Current (6 µA maximum)
- 16-Byte Page Write Mode:
  - Partial page writes allowed
- Random and Sequential Read Modes
- Self-Timed Write Cycle within 5 ms Maximum
- ESD Protection > 4,000V
- High Reliability:
  - Endurance: 1,000,000 write cycles
  - Data retention: 100 years
- RoHS Compliant
- Die Sale Options: Wafer Form

Packages

- 8-Lead PDIP, 8-Lead SOIC, 5-Lead SOT23, 8-Lead TSSOP, 8-Pad UDFN and 8-Ball VFBGA

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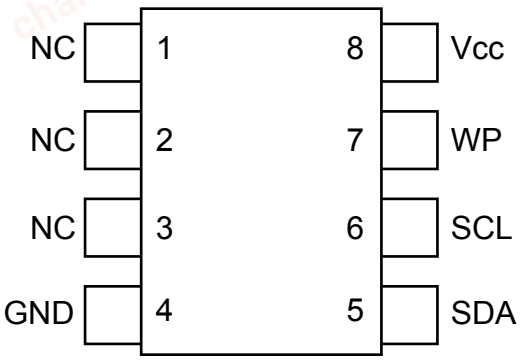
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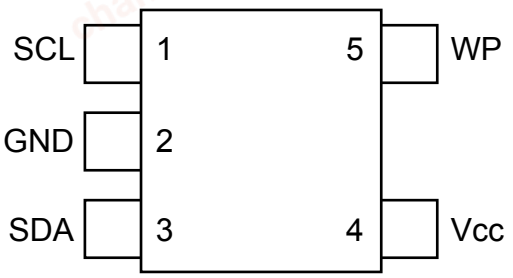
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1. Package Types (not to scale)

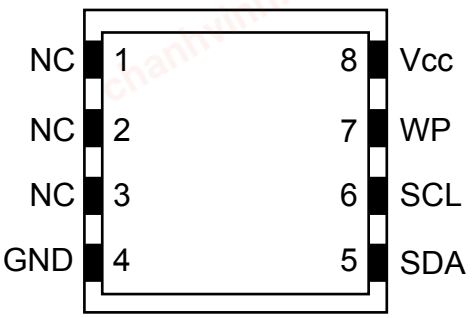
8-Lead PDIP/SOIC/TSSOP
(Top View)



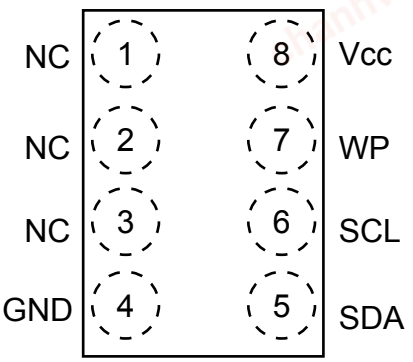
5-Lead SOT23
(Top View)



8-Pad UDFN
(Top View)



8-Ball VFBGA
(Top View)



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2. Pin Descriptions

The descriptions of the pins are listed in Table 2-1.

Table 2-1. Pin Function Table

Name	8-Lead PDIP	8-Lead SOIC	5-Lead SOT23	8-Lead TSSOP	8-Pad UDFN(1)	8-Ball VFBGA	Function
NC	1	1	—	1	1	1	No Connect
NC	2	2	—	2	2	2	No Connect
NC	3	3	—	3	3	3	No Connect
GND	4	4	2	4	4	4	Ground
SDA	5	5	3	5	5	5	Serial Data
SCL	6	6	1	6	6	6	Serial Clock
WP(2)	7	7	5	7	7	7	Write-Protect
V_{CC}	8	8	4	8	8	8	Device Power Supply

Notes:

1. The exposed pad on this package can be connected to GND or left floating.
2. If the WP pin is not driven, it is internally pulled down to GND. To operate in a wide variety of application environments, the pull-down mechanism is intentionally designed to be somewhat strong. Once this pin is biased above the CMOS input buffer's trip point (~0.5 x VCC), the pull-down mechanism disengages. Microchip recommends connecting this pin to a known state whenever possible.

2.1 Ground

The ground reference for the power supply. GND should be connected to the system ground.

2.2 Serial Data (SDA)

The SDA pin is an open-drain bidirectional input/output pin used to serially transfer data to and from the device. The SDA pin must be pulled high using an external pull-up resistor (not to exceed 10 kΩ in value) and may be wire-ORed with any number of other open-drain or open-collector pins from other devices on the same bus.

2.3 Serial Clock (SCL)

The SCL pin is used to provide a clock to the device and to control the flow of data to and from the device. Command and input data present on the SDA pin are always latched in on the rising edge of SCL, while output data on the SDA pin are clocked out on the falling edge of SCL. The SCL pin must either be forced high when the serial bus is idle or pulled high using an external pull-up resistor.

2.4 Write-Protect (WP)

The write-protect input, when connected to GND, allows normal write operations. When the WP pin is connected directly to V_{CC}, all write operations to the protected memory are inhibited.

If the pin is left floating, the WP pin will be internally pulled down to GND. However, due to capacitive coupling that may appear in customer applications, Microchip recommends always connecting the WP pin to a known state. When using a pull-up resistor, Microchip recommends using 10 kΩ or less.

Table 2-2. Write-Protect

WP Pin Status	Part of the Array Protected
At V_{CC}	Full Array
At GND	Normal Write Operations

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2.5 Device Power Supply (V_{CC})

The Device Power Supply (V_{CC}) pin is used to supply the source voltage to the device. Operations at invalid V_{CC} voltages may produce spurious results and should not be attempted.

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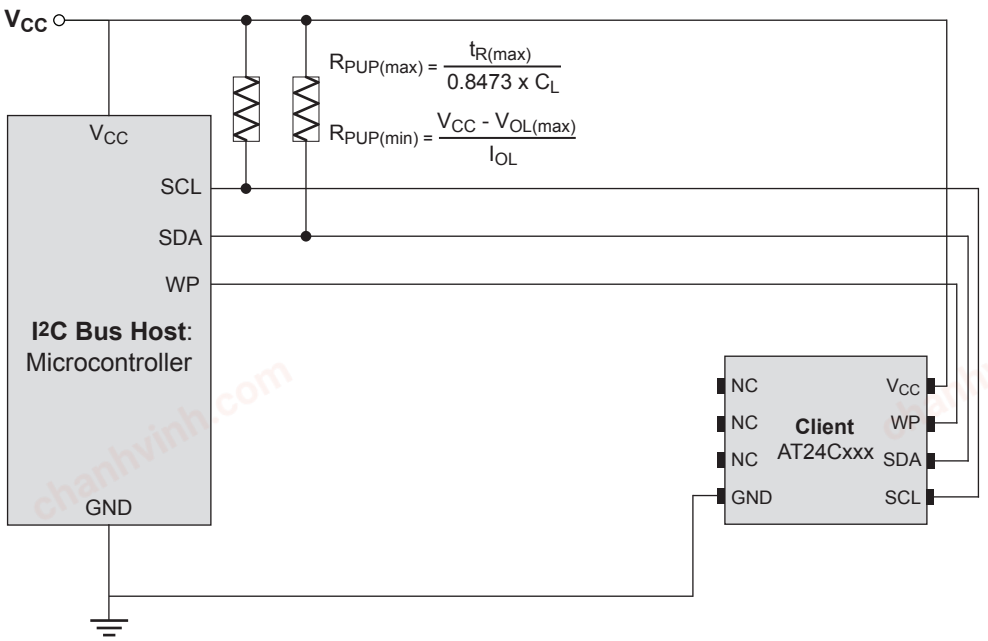
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3. Description

The AT24C16C provides 16,384 bits of Serial Electrically Erasable and Programmable Read-Only Memory (EEPROM) organized as 2,048 words of 8 bits each. This device is optimized for use in many industrial and commercial applications where low-power and low-voltage operations are essential. The device is available in space-saving 8-lead PDIP, 8-lead SOIC, 5-lead SOT23, 8-lead TSSOP, 8-pad UDFN and 8-ball VFBGA packages. All packages operate from 1.7V to 5.5V.

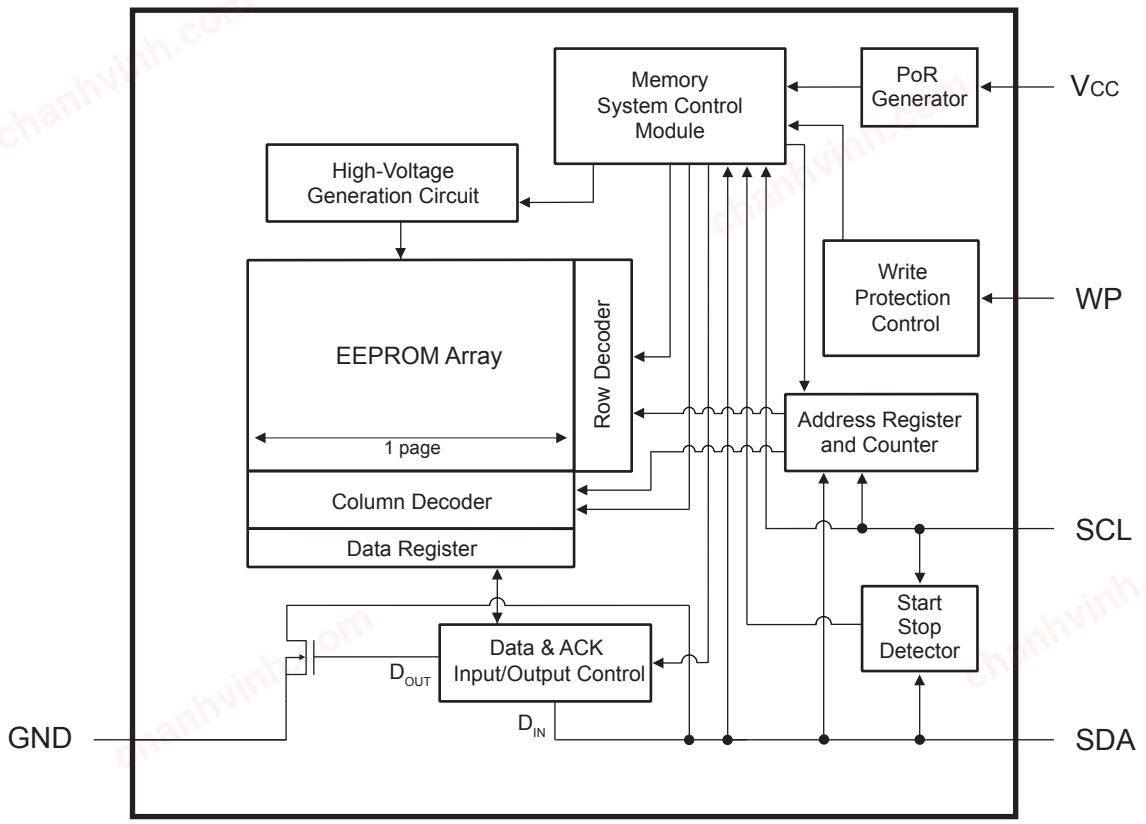
3.1 System Configuration Using Two-Wire Serial EEPROMs



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3.2 Block Diagram



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4. Electrical Characteristics

4.1 Absolute Maximum Ratings

Temperature under bias	-55°C to +125°C
Storage temperature	-65°C to +150°C
Vcc	6.25V
Voltage on any pin with respect to ground	-1.0V to +7.0V
DC output current	5 mA
ESD protection	>4 kV

Note: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at these or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

4.2 DC and AC Operating Range

Table 4-1. DC and AC Operating Range

AT24C16C		
Operating Temperature (Case)	Industrial Temperature Range	-40°C to +85°C
V_{CC} Power Supply	Low-Voltage Grade	1.7V to 5.5V

4.3 DC Characteristics

Table 4-2. DC Characteristics

Parameter	Symbol	Minimum	Maximum	Units	Test Conditions
Supply Voltage	V_{CC}	1.7	5.5	V	
Supply Current	I_{CC1}	—	1.0	mA	V_{CC} = 5.0V, Write at 100 kHz
Supply Current	I_{CC2}	—	3.0	mA	V_{CC} = 5.0V, Write at 100 kHz
Standby Current	I_{SB}	—	1.0	µA	V_{CC} = 1.7V, V_{IN} = V_{CC} or GND
		—	6.0	µA	V_{CC} = 5.5V, V_{IN} = V_{CC} or GND
Input Leakage Current	I_{LI}	—	3.0	µA	V_{IN} = V_{CC} or GND
Output Leakage Current	I_{LO}	—	3.0	µA	V_{OUT} = V_{CC} or GND
Input Low Level	V_{IL}	-0.6	V_{CC} x 0.3	V	Note 1
Input High Level	V_{IH}	V_{CC} x 0.7	V_{CC} + 0.5	V	Note 1
Output Low Level	V_{OL1}	—	0.2	V	V_{CC} = 1.7V, I_{OL} = 0.15 mA
Output Low Level	V_{OL2}	—	0.4	V	V_{CC} = 3.0V, I_{OL} = 2.1 mA

Note:

1. This parameter is characterized but is not 100% tested in production.

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4.4 AC Characteristics

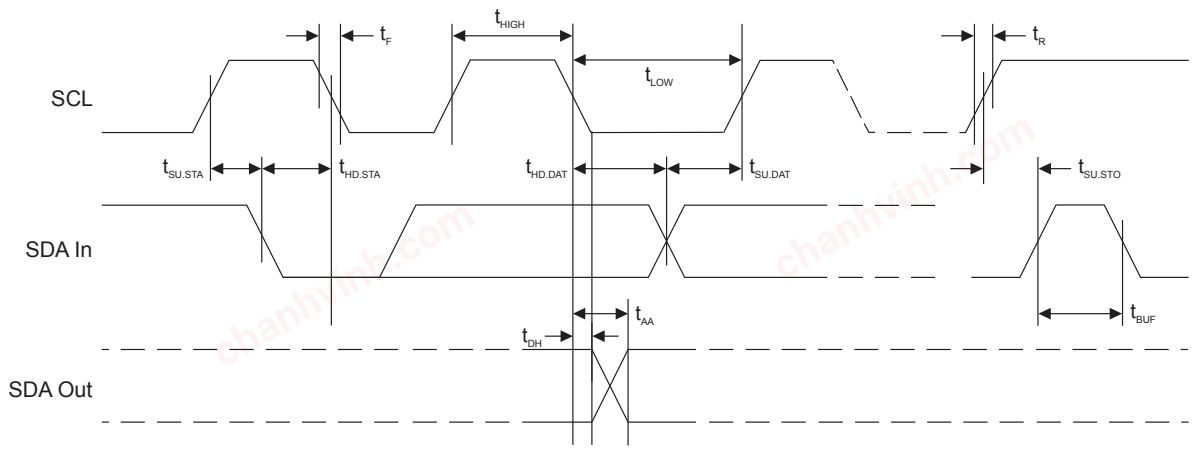
Table 4-3. AC Characteristics

Parameter	Symbol	Fast Mode		Fast Mode Plus		Units
		V_{CC} = 1.7V to 5.5V		V_{CC} = 2.5V to 5.5V		
		Min.	Max.	Min.	Max.	
Clock Frequency, SCL	f_{SCL}	—	400	—	1000	kHz
Clock Pulse Width Low	t_{LOW}	1,200	—	500	—	ns
Clock Pulse Width High	t_{HIGH}	600	—	400	—	ns
Input Filter Spike Suppression	t_I	—	100	—	50	ns
Clock Low to Data Out Valid	t_{AA}	100	900	50	450	ns
Bus Free Time between Stop and Start	t_{BUF}	1,200	—	500	—	ns
Start Hold Time	$t_{HD.STA}$	600	—	250	—	ns
Start Set-Up Time	$t_{SU.STA}$	600	—	250	—	ns
Data In Hold Time	$t_{HD.DAT}$	0	—	0	—	ns
Data In Set-up Time	$t_{SU.DAT}$	100	—	100	—	ns
Inputs Rise Time(2)	t_R	—	300	—	300	ns
Inputs Fall Time(2)	t_F	—	300	—	100	ns
Stop Set-Up Time	$t_{SU.STO}$	600	—	250	—	ns
Data Out Hold Time	t_{DH}	50	—	50	—	ns
Write Cycle Time	t_{WR}	—	5	—	5	ms

Notes:

1. AC measurement conditions:
   - C_L: 100 pF
   - R_{PUP} (SDA bus line pull-up resistor to V_{CC}): 1.3 kΩ (1000 kHz), 4 kΩ (400 kHz), 10 kΩ (100 kHz)
   - Input rise and fall times: ≤50 ns
   - Input and output timing reference voltages: 0.5 x V_{CC}
2. These parameters are determined through product characterization and are not 100% tested in production.

Figure 4-1. Bus Timing



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4.5 Electrical Specifications

4.5.1 Power-Up Requirements and Reset Behavior

During a power-up sequence, the V_{CC} supplied to the AT24C16C should monotonically rise from GND to the minimum V_{CC} level (as specified in Table 4-1), with a slew rate no faster than 0.1 V/µs.

4.5.1.1 Device Reset

To prevent inadvertent write operations or other spurious events from occurring during a power-up sequence, the AT24C16C includes a Power-on Reset (POR) circuit. Upon power-up, the device will not respond to any commands until the V_{CC} level crosses the internal voltage threshold (V_{POR}) that brings the device out of Reset and into Standby mode.

The system designer must ensure the instructions are not sent to the device until the V_{CC} supply has reached a stable value greater than or equal to the minimum V_{CC} level. Additionally, once the V_{CC} is greater than or equal to the minimum V_{CC} level, the bus host must wait at least t_{PUP} before sending the first command to the device. See Table 4-4 for the values associated with these power-up parameters.

Table 4-4. Power-up Conditions[1]

Symbol	Parameter	Min.	Max.	Units
t_{PUP}	Time required after V_{CC} is stable before the device can accept commands	100	—	µs
V_{POR}	Power-on Reset Threshold Voltage	—	1.5	V
t_{POFF}	Minimum time at V_{CC} = 0V between power cycles	0.03	—	ms

Note:

1. These parameters are characterized but are not 100% tested in production.

If an event occurs in the system where the V_{CC} level supplied to the AT24C16C drops below the maximum V_{POR} level specified, it is recommended that a full power cycle sequence be performed. First, drive the V_{CC} pin to GND, waiting at least the minimum t_{POFF} time, and then perform a new power-up sequence in compliance with the requirements defined in this section.

4.5.2 Pin Capacitance

Table 4-5. Pin Capacitance[1]

Symbol	Test Condition	Max.	Units	Conditions
$C_{I/O}$	Input/Output Capacitance (SDA)	8	pF	$V_{I/O}$ = 0V
C_{IN}	Input Capacitance (SCL)	6	pF	V_{IN} = 0V

Note:

1. This parameter is characterized but is not 100% tested in production.

4.5.3 EEPROM Cell Performance Characteristics

Table 4-6. EEPROM Cell Performance Characteristics

Operation	Test Condition	Min.	Max.	Units
Write Endurance[1]	T_A = +25°C, V_{CC} = 5.5V, Page Write mode	1,000,000	—	Write Cycles
Data Retention[1]	T_A = +55°C	100	—	Years

Note:

1. Performance is determined through characterization and the qualification process.

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5. Device Operation and Communication

The AT24C16C operates as a client device and utilizes a simple I²C-compatible Two-Wire digital serial interface to communicate with a host controller, commonly referred to as the bus host. The host initiates and controls all read and write operations to the client devices on the serial bus, and both the host and the client devices can transmit and receive data on the bus.

The serial interface consists of two signal lines: Serial Clock (SCL) and Serial Data (SDA). The SCL pin is used to receive the clock signal from the host, while the bidirectional SDA pin is used to receive command and data information from the host as well as to send data back to the host. Data are always latched into the AT24C16C on the rising edge of SCL and always output from the device on the falling edge of SCL. Both the SCL and SDA pins incorporate integrated spike suppression filters and Schmitt Triggers to minimize the effects of input spikes and bus noise.

All command and data information is transferred with the Most Significant bit (MSb) first. During bus communication, one data bit is transmitted every clock cycle, and after eight bits (one byte) of data have been transferred, the receiving device must respond with either an Acknowledge (ACK) or a No-Acknowledge (NACK) response bit during a ninth clock cycle (ACK/NACK clock cycle) generated by the host. Therefore, nine clock cycles are required for every one byte of data transferred. There are no unused clock cycles during any read or write operation; thus, there must not be any interruptions or breaks in the data stream during each data byte transfer and ACK or NACK clock cycle.

During data transfers, data on the SDA pin must change only while SCL is low, and the data must remain stable while SCL is high. If data on the SDA pin changes while SCL is high, then either a Start or a Stop condition will occur. Start and Stop conditions are used to initiate and terminate all serial bus communication between the host and the client devices. The number of data bytes transferred between a Start and a Stop condition is not limited and is determined by the host. For the serial bus to be idle, both the SCL and SDA pins must be in the logic high state simultaneously.

5.1 Clock and Data Transition Requirements

The SDA pin is an open-drain terminal and therefore must be pulled high with an external pull-up resistor. SCL is an input pin that can either be driven high or pulled high using an external pull-up resistor. Data on the SDA pin may change only during SCL low time periods. Data changes during SCL high periods will indicate a Start or Stop condition as defined below. The relationship of the AC timing parameters with respect to SCL and SDA for the AT24C16C are shown in the timing waveform in Figure 4-1. The AC timing characteristics and specifications are outlined in AC Characteristics.

5.2 Start and Stop Conditions

5.2.1 Start Condition

A Start condition occurs when there is a high-to-low transition on the SDA pin while the SCL pin is at a stable logic '1' state, which will bring the device out of Standby mode. The host initiates any data transfer sequence with a Start condition; thus, every command must commence with this condition. The device continuously monitors the SDA and SCL pins for a Start condition and will only respond when one is detected. Refer to Figure 5-1 for more details.

5.2.2 Stop Condition

A Stop condition occurs when there is a low-to-high transition on the SDA pin while the SCL pin is stable in the logic '1' state.

The host can use the Stop condition to end a data transfer sequence with the AT24C16C, which will subsequently return to Standby mode. The host can also utilize a repeated Start condition instead of a Stop condition to end the current data transfer if the host will perform another operation. Refer to Figure 5-1 for more details.

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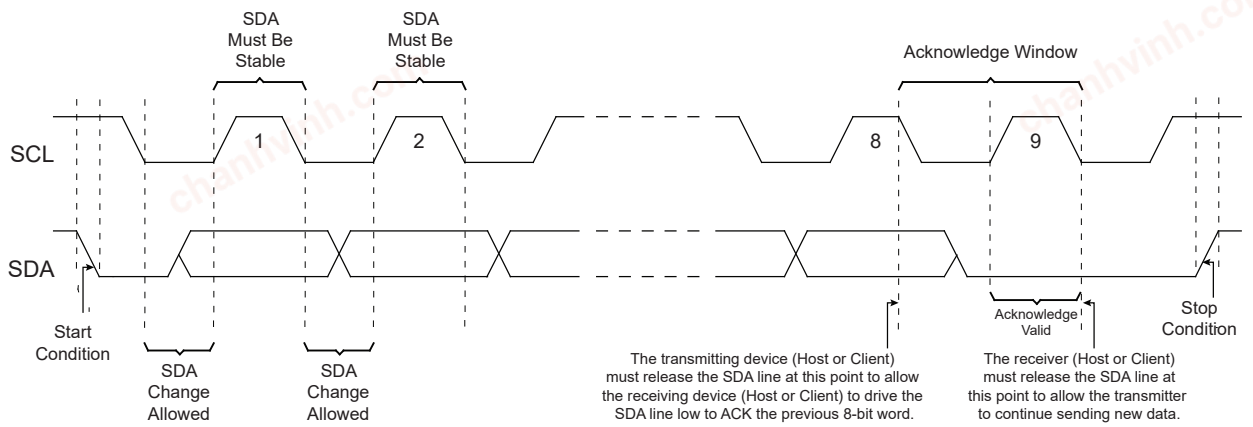
5.3 Acknowledge and No-Acknowledge

After each byte of data is received, the receiving device must confirm with the transmitting device that it has successfully received the data byte by responding with an Acknowledge (ACK). An ACK occurs when the transmitting device releases the SDA line at the falling edge of the eighth clock cycle, followed by the receiving device responding with a logic '0' throughout the ninth clock cycle's high period.

When the AT24C16C transmits data to the host, the host can indicate that it has finished receiving data and wants to end the operation by sending a logic '1' response to the AT24C16C instead of an ACK response during the ninth clock cycle. This is known as a No-Acknowledge (NACK) and is accomplished when the host sends a logic '1' during the ninth clock cycle, at which point the AT24C16C will release the SDA line so the host can then generate a Stop condition.

The transmitting device, which can be either the bus host or the Serial EEPROM, must release the SDA line at the falling edge of the eighth clock cycle to allow the receiving device to drive the SDA line to a logic '0' to ACK the previous 8-bit word. The receiving device must release the SDA line at the end of the ninth clock cycle to allow the transmitter to continue sending new data. A timing diagram is provided in Figure 5-1 to better illustrate these requirements.

Figure 5-1. Start Condition, Data Transitions, Stop Condition and Acknowledge



5.4 Standby Mode

The AT24C16C features a low-power Standby mode that is enabled when any one of the following occurs:

- A valid power-up sequence is performed (see Power-Up Requirements and Reset Behavior).
- A Stop condition at the end of a valid I^2C transaction is received by the device unless it initiates an internal write cycle (see Write Operations).
- An internal write cycle is completed (see Write Operations).

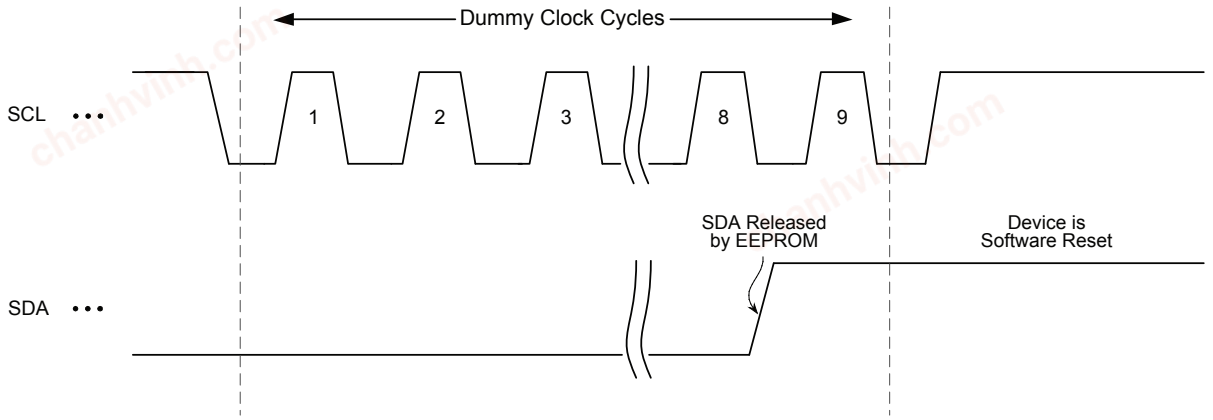
5.5 Software Reset

After an interruption in protocol, power loss or system Reset, any Two-Wire device can be protocol reset by clocking SCL until SDA is released by the EEPROM and goes high. The number of clock cycles until SDA is released by the EEPROM will vary. The software Reset sequence should not take more than nine dummy clock cycles. Once the software Reset sequence is complete, a new protocol can be sent to the device by sending a Start condition followed by the protocol. Refer to Figure 5-2 for an illustration.

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Figure 5-2. Software Reset



In the event that the device is still non-responsive or remains active on the SDA bus, a power cycle must be used to reset the device (see Power-Up Requirements and Reset Behavior).

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6. Memory Organization

The AT24C16C is internally organized as 128 pages of 16 bytes each.

6.1 Device Addressing

Accessing the device requires an 8-bit device address byte following a Start condition to enable the device for a read or write operation.

The Most Significant four bits of the device address byte are referred to as the device type identifier. The device type identifier '1010' (Ah) is required in bits 7 through 4 of the device address byte (see Table 6-1).

Following the 4-bit device type identifier in the bit 3, bit 2 and bit 1 positions of the device address byte are bits A10, A9 and A8, which are the three Most Significant bits of the memory array word address.

The eighth bit (bit 0) of the device address byte is the Read/Write Select bit. A read operation is initiated if this bit is high and a write operation is initiated if this bit is low.

Upon the successful comparison of the device address byte, the AT24C16C will return an ACK. If a valid comparison is not made, the device will NACK.

Table 6-1. Device Address Byte

Package	Device Type Identifier				Most Significant Bits of the Word Address			R/$\overline{W}$ Select
	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
All Package Types	1	0	1	0	A10	A9	A8	R/$\overline{W}$

For all operations except the current address read, a word address byte must be transmitted to the device immediately following the device address byte. The word address byte consists of the remaining eight bits of the 11-bit memory array word address and is used to specify which byte location in the EEPROM to start reading or writing. Refer to Table 6-2 to review these bit positions.

Table 6-2. Word Address Byte

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
A7	A6	A5	A4	A3	A2	A1	A0

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7. Write Operations

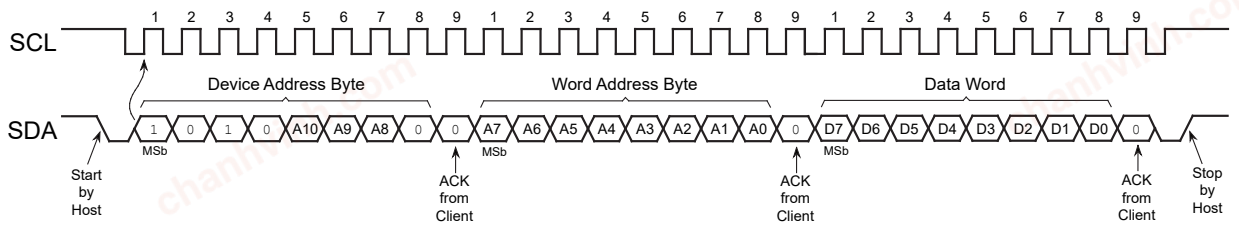
All write operations for the AT24C16C begin with the host sending a Start condition, followed by a device address byte with the R/$\overline{W}$ bit set to logic '0', and then by the word address byte. The data value(s) to be written to the device immediately follow the word address byte.

7.1 Byte Write

The AT24C16C supports the writing of a single 8-bit byte. Selecting a data word in the AT24C16C requires an 11-bit word address.

Upon receipt of the proper device address and word address bytes, the EEPROM will send an Acknowledge. The device will then be ready to receive the 8-bit data word. After receiving the 8-bit data word, the EEPROM will respond with an ACK. The addressing device, such as a bus host, must then terminate the write operation with a Stop condition. At this point, the EEPROM will enter an internally self-timed write cycle, which will be completed within t_{WR}, while the data word is being programmed into the nonvolatile EEPROM. All inputs are disabled during this write cycle, and the EEPROM will not respond until the write is complete.

Figure 7-1. Byte Write



7.2 Page Write

A page write operation allows up to 16 bytes to be written in a single write cycle, provided that all bytes are in the same row of the memory array (where address bits A10 through A4 are identical). Partial page writes of fewer than 16 bytes are also allowed.

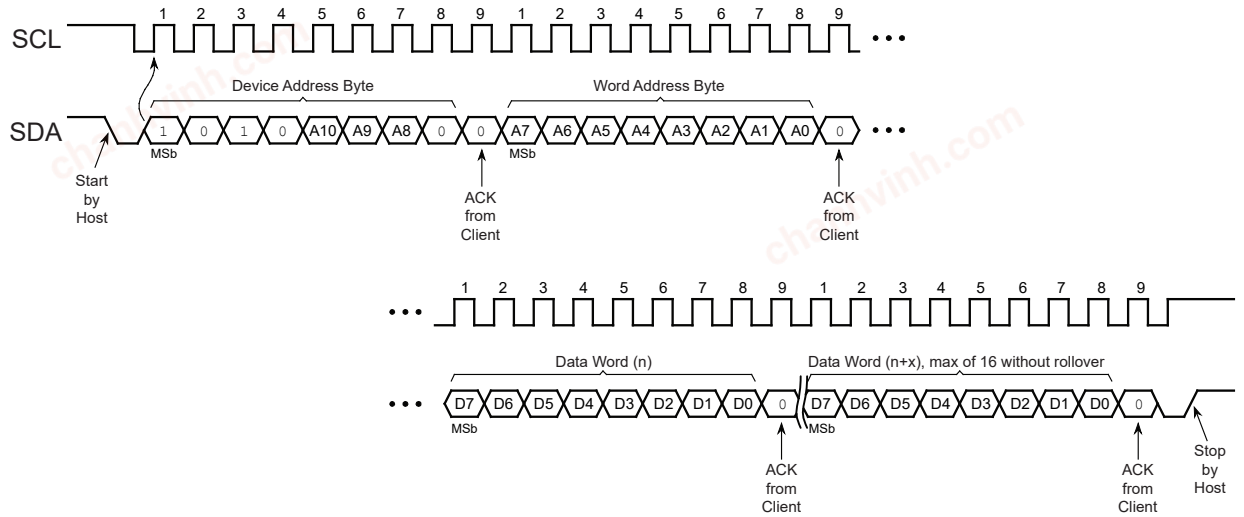
A page write is initiated the same way as a byte write, but the bus host does not send a Stop condition after the first data word is clocked in. Instead, after the EEPROM acknowledges receipt of the first data word, the bus host can transmit up to fifteen additional data words. The EEPROM will respond with an ACK after each data word is received. Once all data to be written have been sent to the device, the bus host must issue a Stop condition (see Figure 7-2), at which point the internally self-timed write cycle will begin.

The lower four bits of the word address are internally incremented following the receipt of each data word. The higher-order address bits are not incremented and retain the memory page row location. Page write operations are limited to writing bytes within a single physical page, regardless of the number of bytes being written. When the incremented word address reaches the page boundary, the address counter will roll over to the beginning of the same page. Nevertheless, creating a rollover event should be avoided as previously loaded data in the page could become unintentionally altered.

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Figure 7-2. Page Write

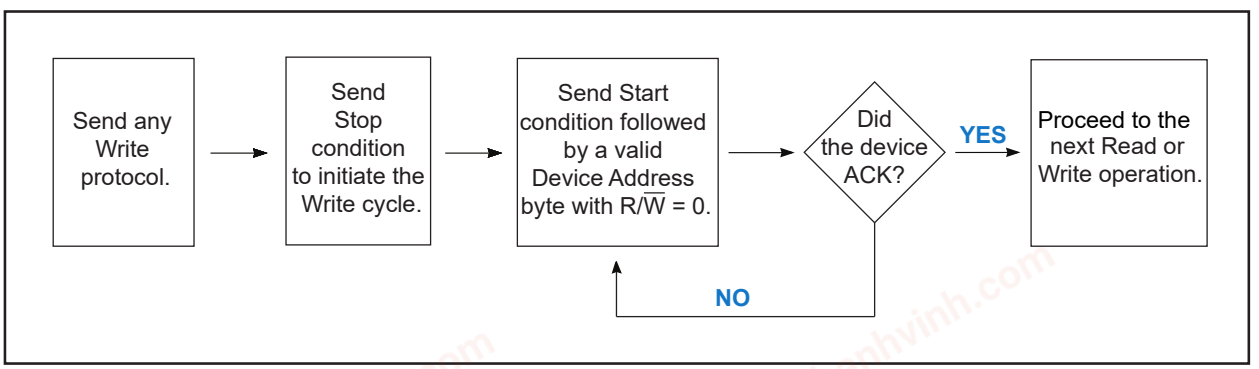


7.3 Acknowledge Polling

An Acknowledge Polling routine can be implemented to optimize time-sensitive applications that would prefer not to wait the fixed maximum write cycle time (t_{WR}). This method allows the application to immediately know when the Serial EEPROM write cycle has completed so a subsequent operation can be started.

Once the internally self-timed write cycle has started, an Acknowledge Polling routine can be initiated. This involves repeatedly sending a Start condition followed by a valid device address byte with the R/$\overline{W}$ bit set to logic '0'. The device will not respond with an ACK while the write cycle is ongoing. Once the internal write cycle has completed, the EEPROM will respond with an ACK, allowing a new read or write operation to be immediately initiated. A flowchart has been included in Figure 7-3 to better illustrate this technique.

Figure 7-3. Acknowledge Polling Flowchart



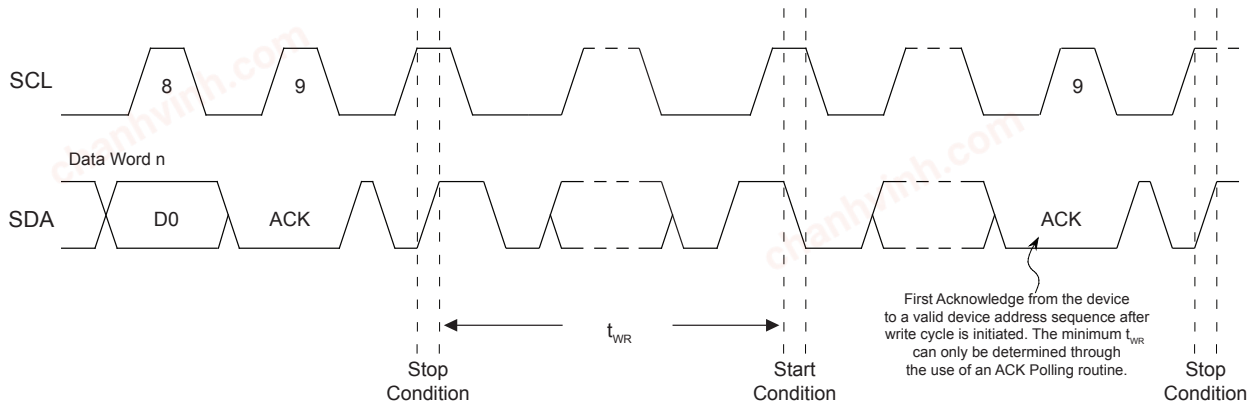
7.4 Write Cycle Timing

The length of the self-timed write cycle (t_{WR}) is defined as the amount of time from the Stop condition, which begins the internal write cycle, to the Start condition of the first device address byte sent to the AT24C16C, to which it subsequently responds with an ACK. Figure 7-4 shows this measurement. During the internally self-timed write cycle, any attempts to read from or write to the memory array will not be processed.

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Figure 7-4. Write Cycle Timing



7.5 Write Protection

The AT24C16C utilizes a hardware data protection scheme that allows the user to write-protect the entire memory contents when the WP pin is at V_{CC} (or a valid V_{IH}). No write protection will be set if the WP pin is at GND or left floating.

Table 7-1. AT24C16C Write-Protect Behavior

WP Pin Voltage	Part of the Array Protected
V_{CC}	Full Array
GND	None — Write Protection Not Enabled

The status of the WP pin is sampled at the Stop condition for every byte write or page write operation prior to the start of an internally self-timed write cycle. Changing the WP pin state after the Stop condition has been sent will not alter or interrupt the execution of the write cycle.

If an attempt is made to write to the device while the WP pin has been asserted, the device will acknowledge the device address, word address and data bytes. However, no write cycle will occur when the Stop condition is issued. The device will immediately be ready to accept a new read or write command.

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8. Read Operations

Read operations are initiated the same way as write operations, with the exception that the Read/Write Select bit in the device address byte must be a logic '1'. There are three read operations:

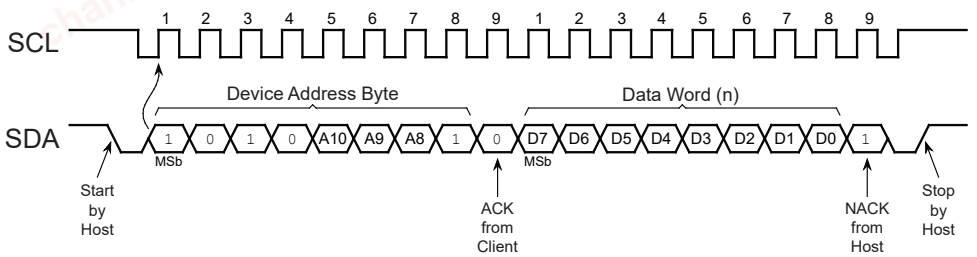
- Current Address Read
- Random Read
- Sequential Read

8.1 Current Address Read

The internal data word address counter maintains the last address accessed during the last read or write operation, incremented by one. This address stays valid between operations as long as the V_{CC} is maintained to the part. The address rollover during a read is from the last byte of the last page to the first byte of the first page of the memory.

A current address read operation will output data according to the location of the internal data word address counter. This is initiated with a Start condition, followed by a valid device address byte with the R/$\overline{W}$ bit set to logic '1'. The device will ACK this sequence and the current address data word is serially clocked out on the SDA line. All types of read operations will be terminated if the bus host does not respond with an ACK (it NACKs) during the ninth clock cycle. After the NACK response, the host may send a Stop condition to complete the protocol, or it can send a Start condition to begin the next sequence.

Figure 8-1. Current Address Read



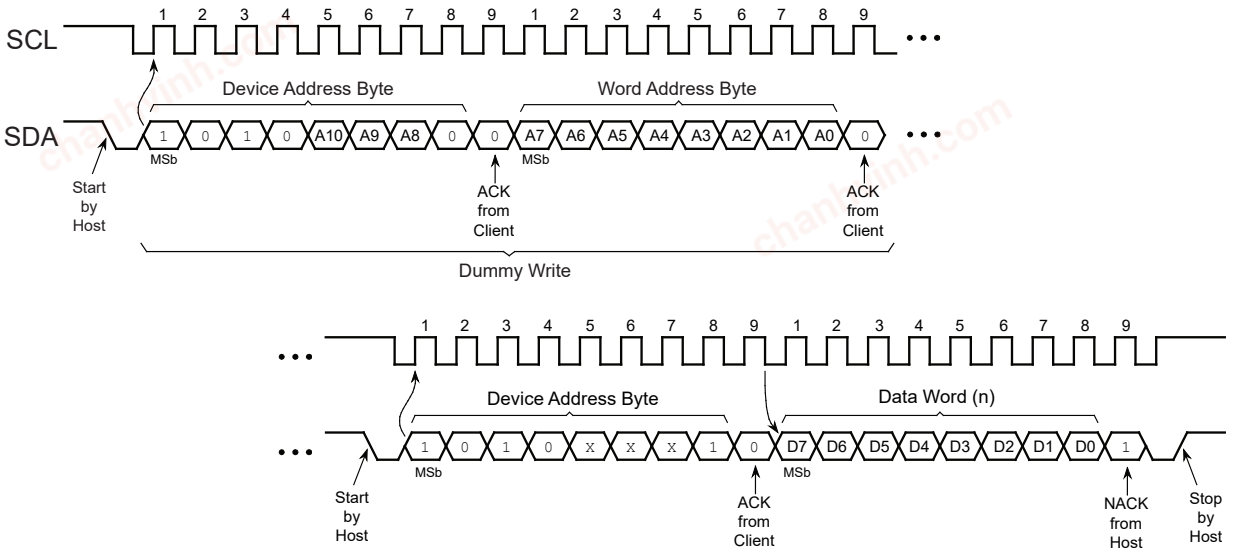
8.2 Random Read

A random read begins in the same way as a byte write operation does to load in a new data word address. This is known as a "dummy write" sequence; however, the data byte and the Stop condition of the byte write must be omitted to prevent the part from entering an internal write cycle. Once the device address and word address are clocked in and acknowledged by the EEPROM, the bus host must generate another Start condition. The bus host now initiates a current address read by sending a Start condition, followed by a valid device address byte with the R/$\overline{W}$ bit set to logic '1'. The EEPROM will ACK the device address and serially clock out the data word on the SDA line. All types of read operations will be terminated if the bus host does not respond with an ACK (it NACKs) during the ninth clock cycle. After the NACK response, the host may send a Stop condition to complete the protocol, or it can send a Start condition to begin the next sequence.

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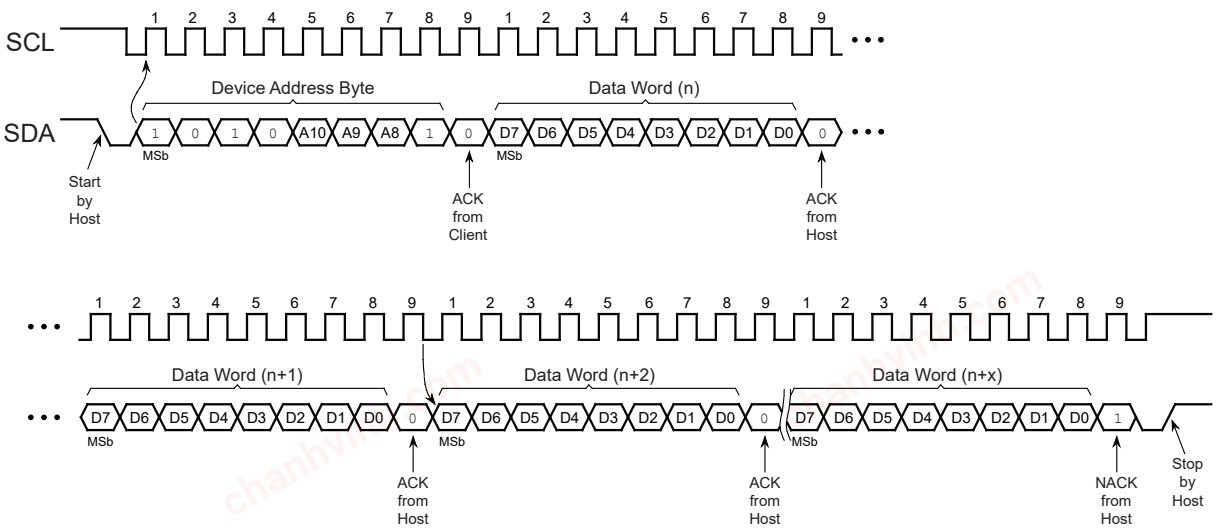
Figure 8-2. Random Read



8.3 Sequential Read

Sequential reads are initiated by either a current address read or a random read. After the bus host receives a data word, it responds with an Acknowledge. As long as the EEPROM receives an ACK, it will continue to increment the word address and serially clock out sequential data words. When the maximum memory address is reached, the data word address will roll over, and the sequential read will continue from the beginning of the memory array. All types of read operations will be terminated if the bus host does not respond with an ACK (it NACKs) during the ninth clock cycle. After the NACK response, the host may send a Stop condition to complete the protocol or it can send a Start condition to begin the next sequence.

Figure 8-3. Sequential Read



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9. Device Default Condition from Microchip

The AT24C16C is delivered with the EEPROM array set to logic '1', resulting in FFh data in all locations.

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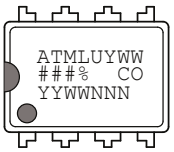
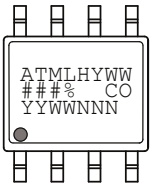
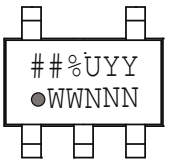
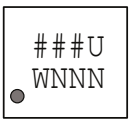
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10. Packaging Information

10.1 Package Marking Information

AT24C16D: Package Marking Information

8-Lead PDIP	8-Lead SOIC	5-Lead SOT23
		
8-Lead TSSOP	**8-Pad UDFN**	**8-Ball VFBGA**
	2.0 x 3.0 mm Body 	1.5 x 2.0 mm Body 

Note 1: ● designates pin 1
Note 2: Package drawings are not to scale
Note 3: For SOT23 package with date codes before 7B, the bottom line (YMXX) is marked on the bottom side, and there is no Country of Assembly (@) mark on the top line

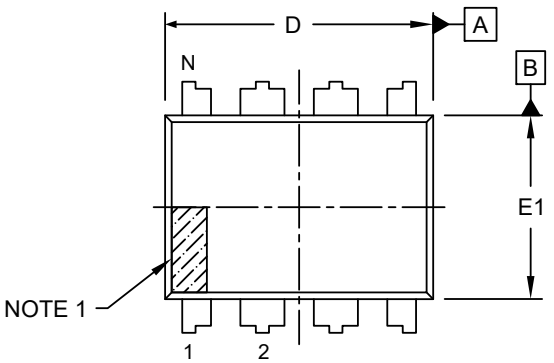
Catalog Number Truncation		
AT24C16D	Truncation Code ###: 16D / ##: AD	
Date Codes		**Voltages**
Y = Year Code (last digit of calendar year) YY = Year Code (last 2 digits of calendar year) WW = Week code (week of January 1 is week '01')		% = Minimum Voltage M: 1.7V min
Country of Origin	**Device Grade**	**Atmel Truncation**
CO = Country of Origin	H or U: Industrial Grade	AT: Atmel ATM: Atmel ATML: Atmel
Trace Code		
NNN = Alphanumeric Trace Code (2 Characters for Small Packages)		

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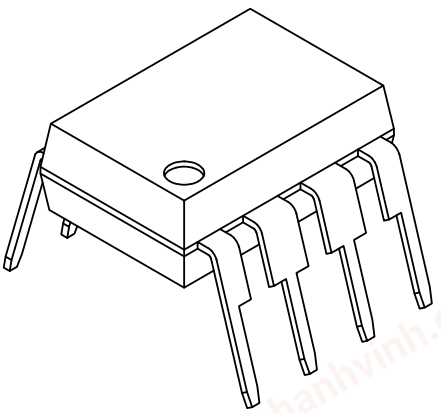
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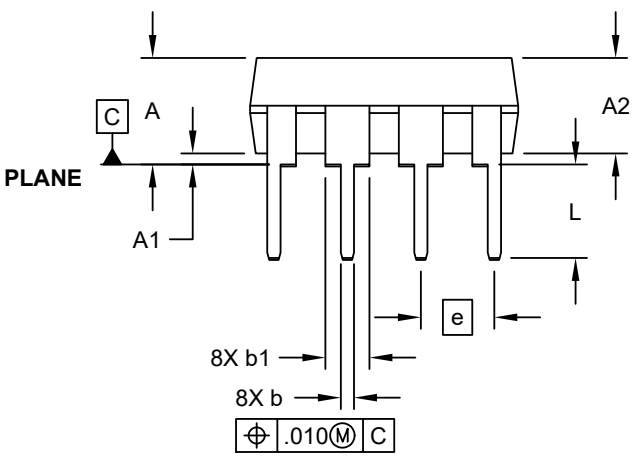
8-Lead Plastic Dual In-Line (P) - 300 mil Body [PDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging

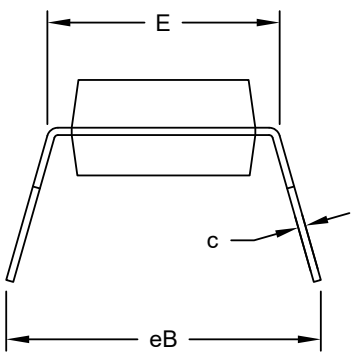


TOP VIEW





SIDE VIEW



END VIEW

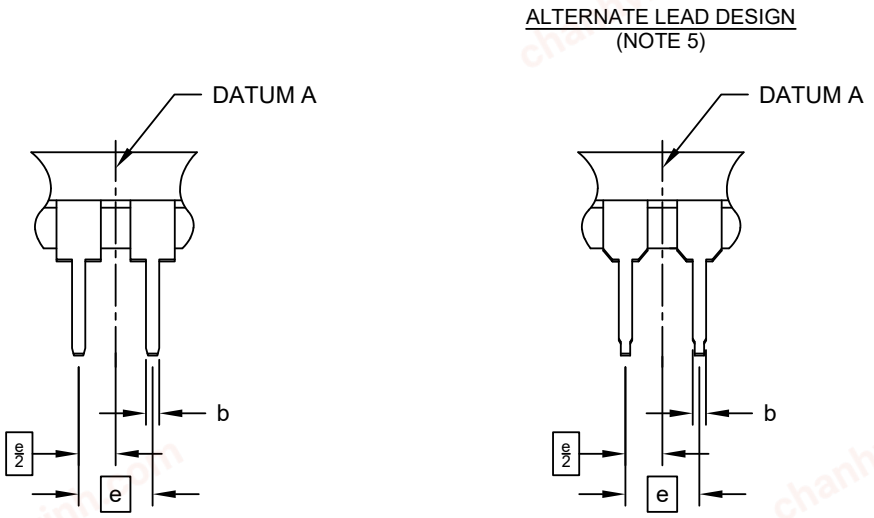
Microchip Technology Drawing No. C04-018-P Rev G Sheet 1 of 2

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8-Lead Plastic Dual In-Line (P) - 300 mil Body [PDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		8	
Pitch	e		.100 BSC	
Top to Seating Plane	A	-	-	.210
Molded Package Thickness	A2	.115	.130	.195
Base to Seating Plane	A1	.015	-	-
Shoulder to Shoulder Width	E	.290	.310	.325
Molded Package Width	E1	.240	.250	.280
Overall Length	D	.348	.365	.400
Tip to Seating Plane	L	.115	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.040	.060	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	-	-	.430

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
5. Lead design above seating plane may vary, based on assembly vendor.

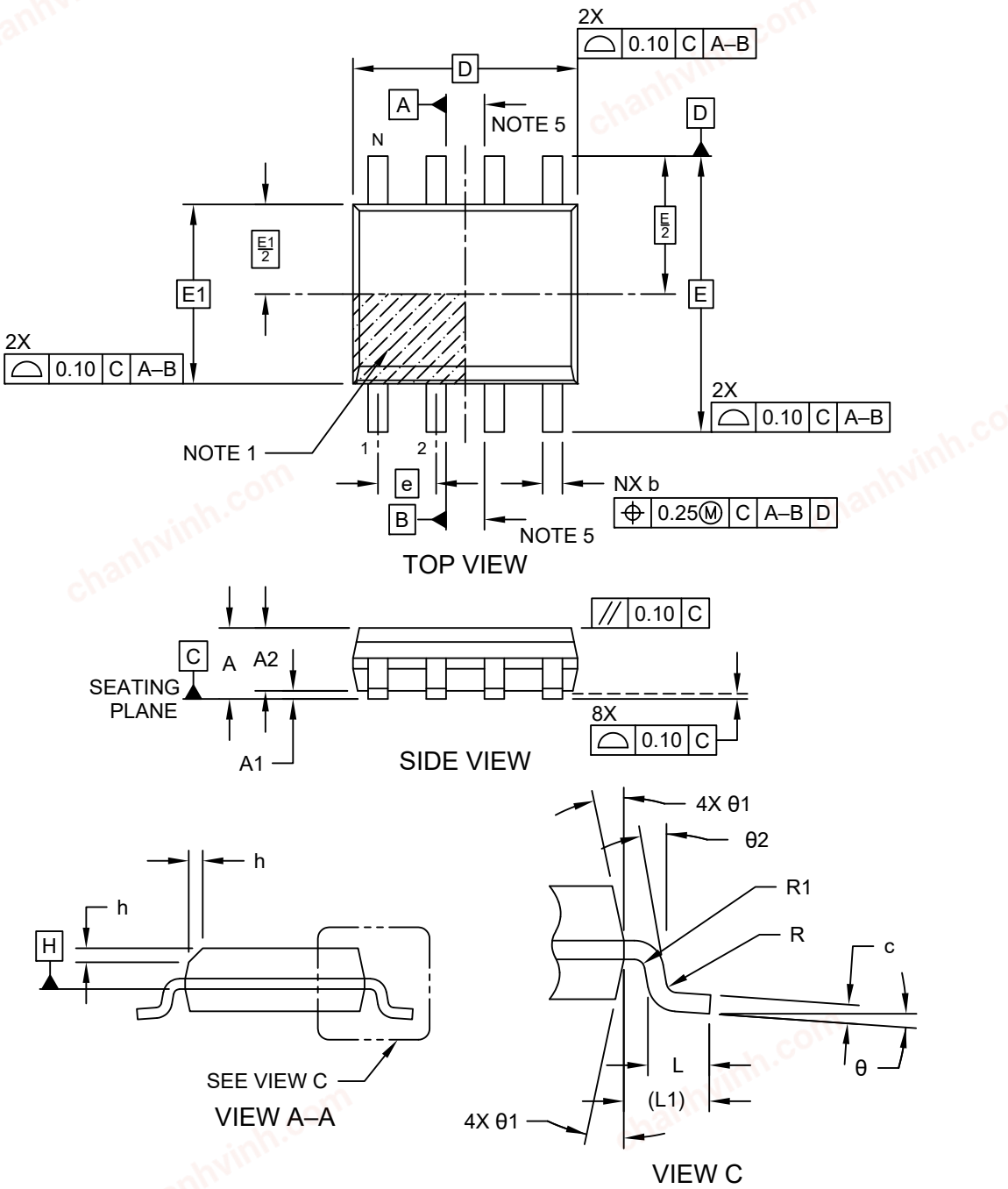
Microchip Technology Drawing No. C04-018-P Rev G Sheet 2 of 2

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8-Lead Plastic Small Outline (SN) - Narrow, 3.90 mm (.150 In.) Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



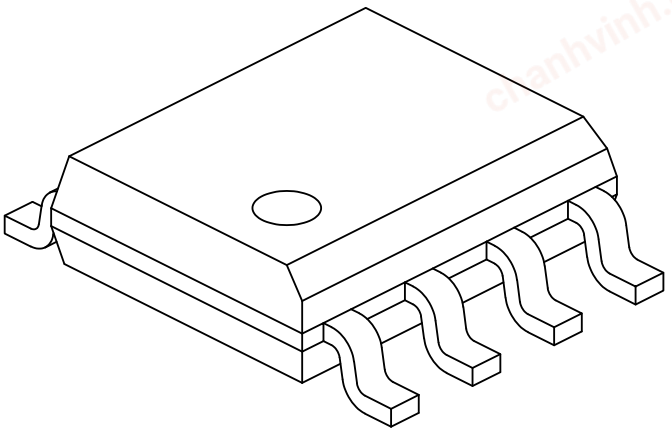
Microchip Technology Drawing No. C04-057-SN Rev K Sheet 1 of 2

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8-Lead Plastic Small Outline (SN) - Narrow, 3.90 mm (.150 In.) Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		8	
Pitch	e		1.27 BSC	
Overall Height	A	–	–	1.75
Molded Package Thickness	A2	1.25	–	-
Standoff §	A1	0.10	–	0.25
Overall Width	E		6.00 BSC	
Molded Package Width	E1		3.90 BSC	
Overall Length	D		4.90 BSC	
Chamfer (Optional)	h	0.25	–	0.50
Foot Length	L	0.40	–	1.27
Footprint	L1		1.04 REF	
Lead Thickness	c	0.17	–	0.25
Lead Width	b	0.31	–	0.51
Lead Bend Radius	R	0.07	–	–
Lead Bend Radius	R1	0.07	–	–
Foot Angle	θ	0°	–	8°
Mold Draft Angle	θ1	5°	–	15°
Lead Angle	θ2	0°	–	–

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.
5. Datums A & B to be determined at Datum H.

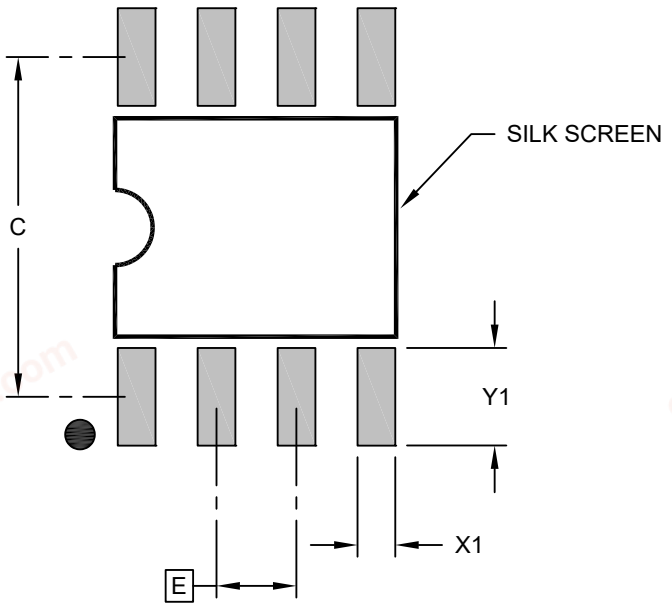
Microchip Technology Drawing No. C04-057-SN Rev K Sheet 2 of 2

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8-Lead Plastic Small Outline (SN) - Narrow, 3.90 mm (.150 In.) Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		1.27 BSC	
Contact Pad Spacing	C		5.40	
Contact Pad Width (X8)	X1			0.60
Contact Pad Length (X8)	Y1			1.55

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

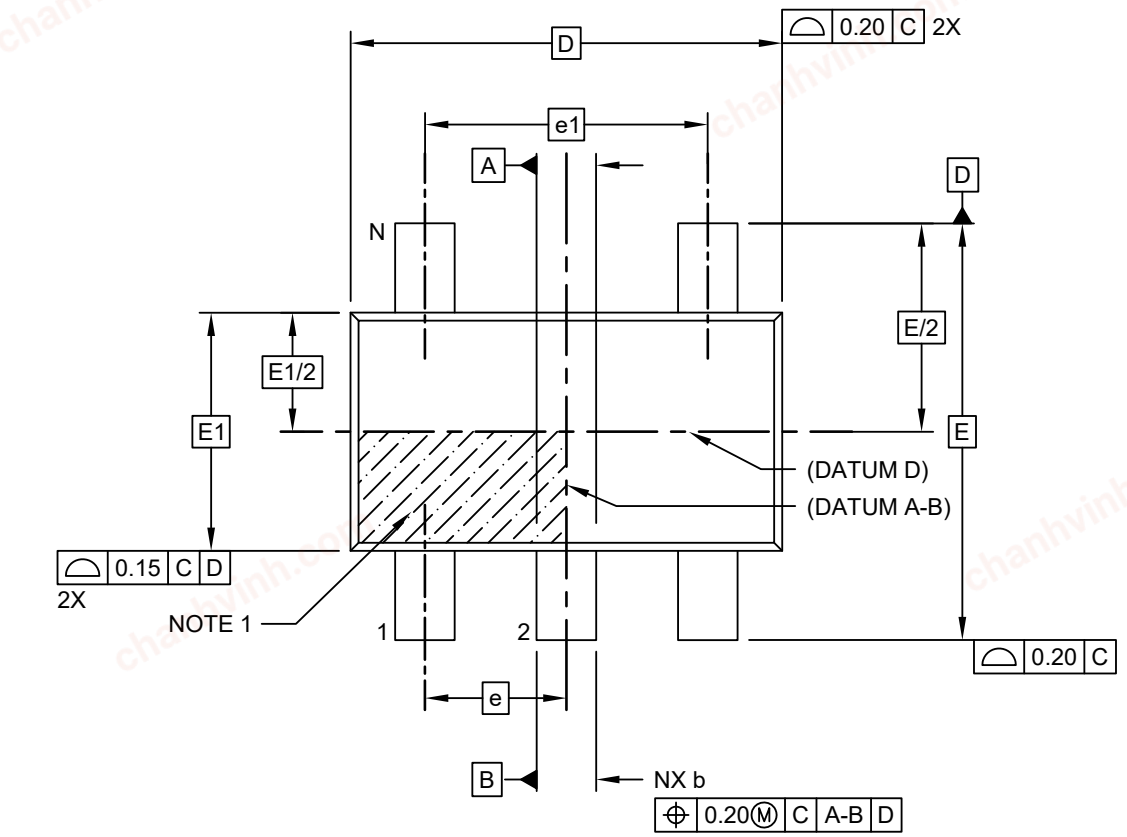
Microchip Technology Drawing C04-2057-SN Rev K

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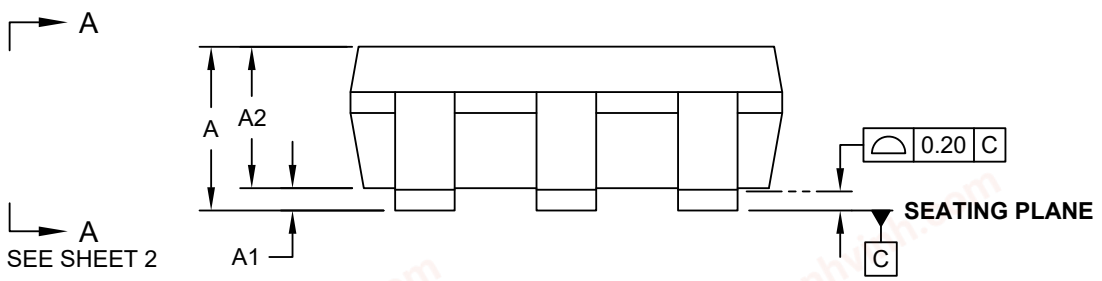
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5-Lead Plastic Thin Small Outline Transistor (NMB) [TSOT]
Atmel Legacy Global Package Code TSZ

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



TOP VIEW



SIDE VIEW

Microchip Technology Drawing C04-21344 Rev B Sheet 1 of 2

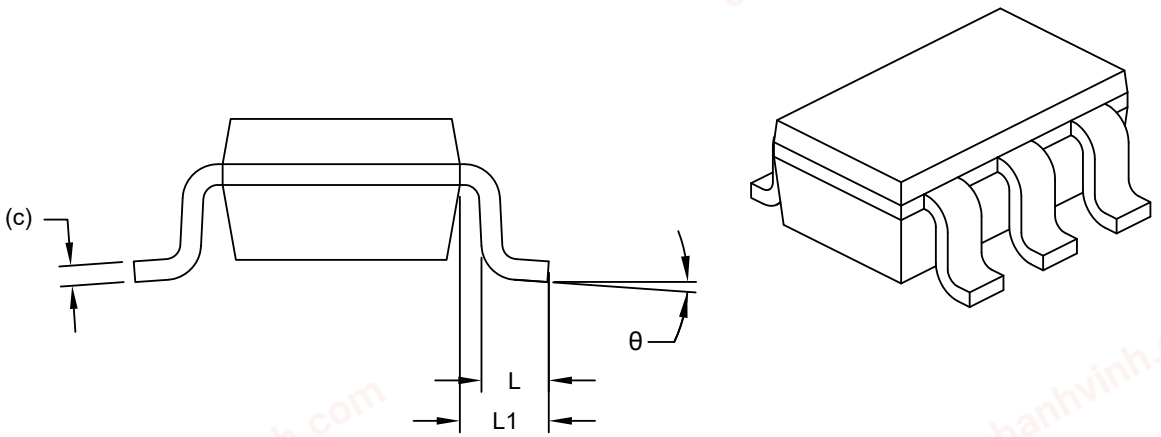
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5-Lead Plastic Thin Small Outline Transistor (NMB) [TSOT]
Atmel Legacy Global Package Code TSZ

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



VIEW A-A
SHEET 1

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		5	
Pitch	e		0.95 BSC	
Outside lead pitch	e1		1.90 BSC	
Overall Height	A	-	-	1.10
Molded Package Thickness	A2	0.70	0.90	1.00
Standoff	A1	-	-	0.10
Overall Width	E		2.80 BSC	
Molded Package Width	E1		1.60 BSC	
Overall Length	D		2.90 BSC	
Foot Length	L	0.30	-	0.60
Footprint	L1		0.60 REF	
Foot Angle	θ	0°	-	8°
Lead Thickness	c	0.08	-	0.20
Lead Width	b	0.30	-	0.50

Notes:

1. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25mm per side.
2. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-21344 Rev B Sheet 2 of 2

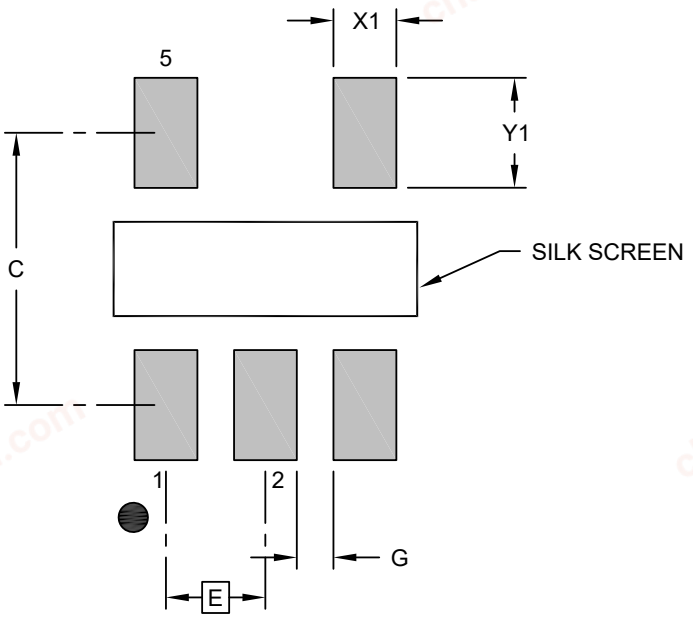
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5-Lead Plastic Thin Small Outline Transistor (NMB) [TSOT]
Atmel Legacy Global Package Code TSZ

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.95 BSC	
Contact Pad Spacing	C		2.60	
Contact Pad Width (X5)	X1			0.60
Contact Pad Length (X5)	Y1			1.05
Contact Pad to Center Pad (X2)	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
2. For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process

Microchip Technology Drawing C04-23344 Rev B

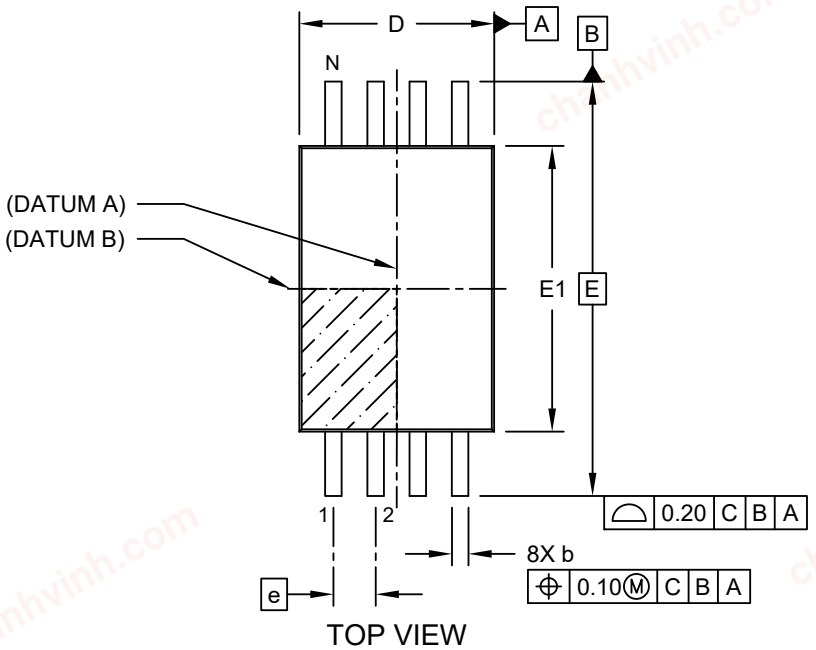
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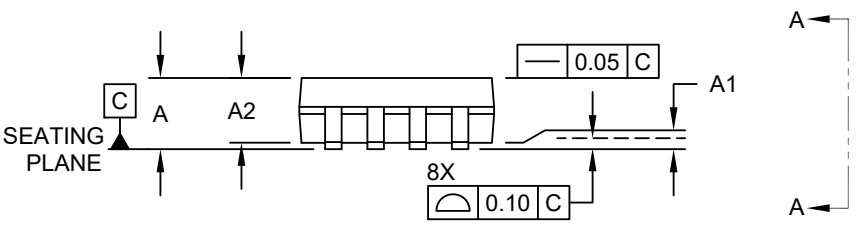
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8-Lead Plastic Thin Shrink Small Outline (ST) - 4.4 mm Body [TSSOP]

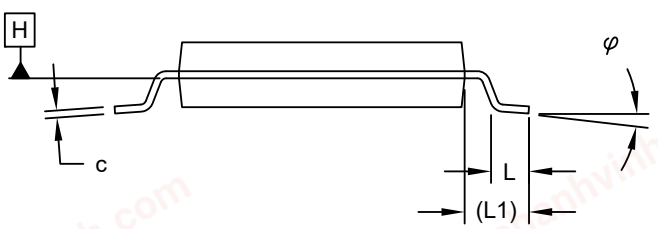
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



TOP VIEW



SIDE VIEW



VIEW A-A

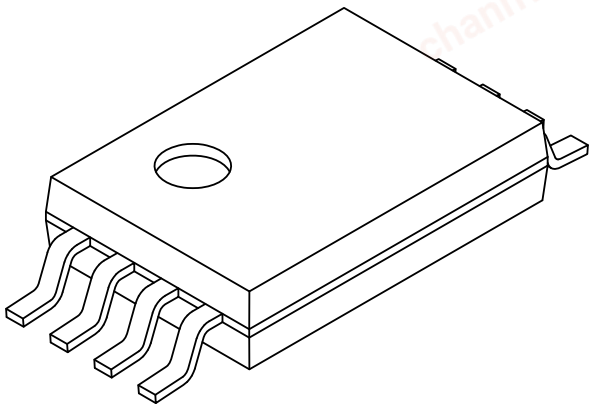
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8-Lead Plastic Thin Shrink Small Outline (ST) - 4.4 mm Body [TSSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		8	
Pitch	e		0.65 BSC	
Overall Height	A	-	-	1.20
Molded Package Thickness	A2	0.80	1.00	1.05
Standoff	A1	0.05	-	-
Overall Width	E		6.40 BSC	
Molded Package Width	E1	4.30	4.40	4.50
Overall Length	D	2.90	3.00	3.10
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Lead Thickness	c	0.09	-	0.25
Foot Angle	φ	0°	4°	8°
Lead Width	b	0.19	-	0.30

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20mm per side.
3. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

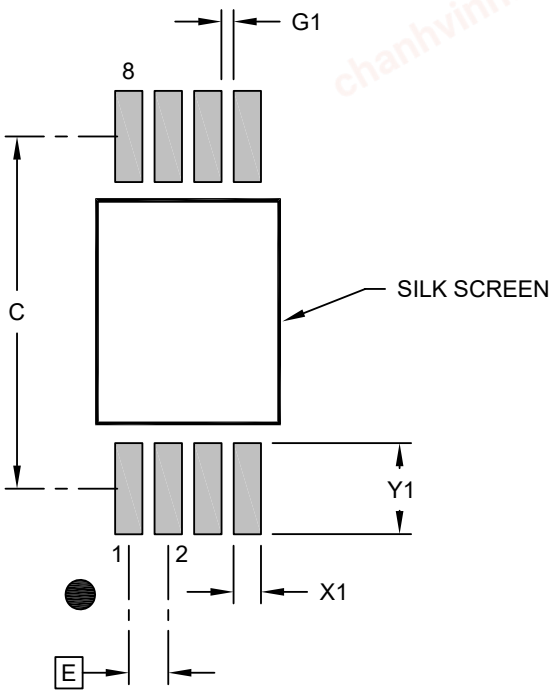
Microchip Technology Drawing C04-086 Rev C Sheet 2 of 2

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8-Lead Plastic Thin Shrink Small Outline (ST) - 4.4 mm Body [TSSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Contact Pad Spacing	C		5.80	
Contact Pad Width (X8)	X1			0.45
Contact Pad Length (X8)	Y1			1.50
Contact Pad to Center Pad (X6)	G1	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
2. For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process

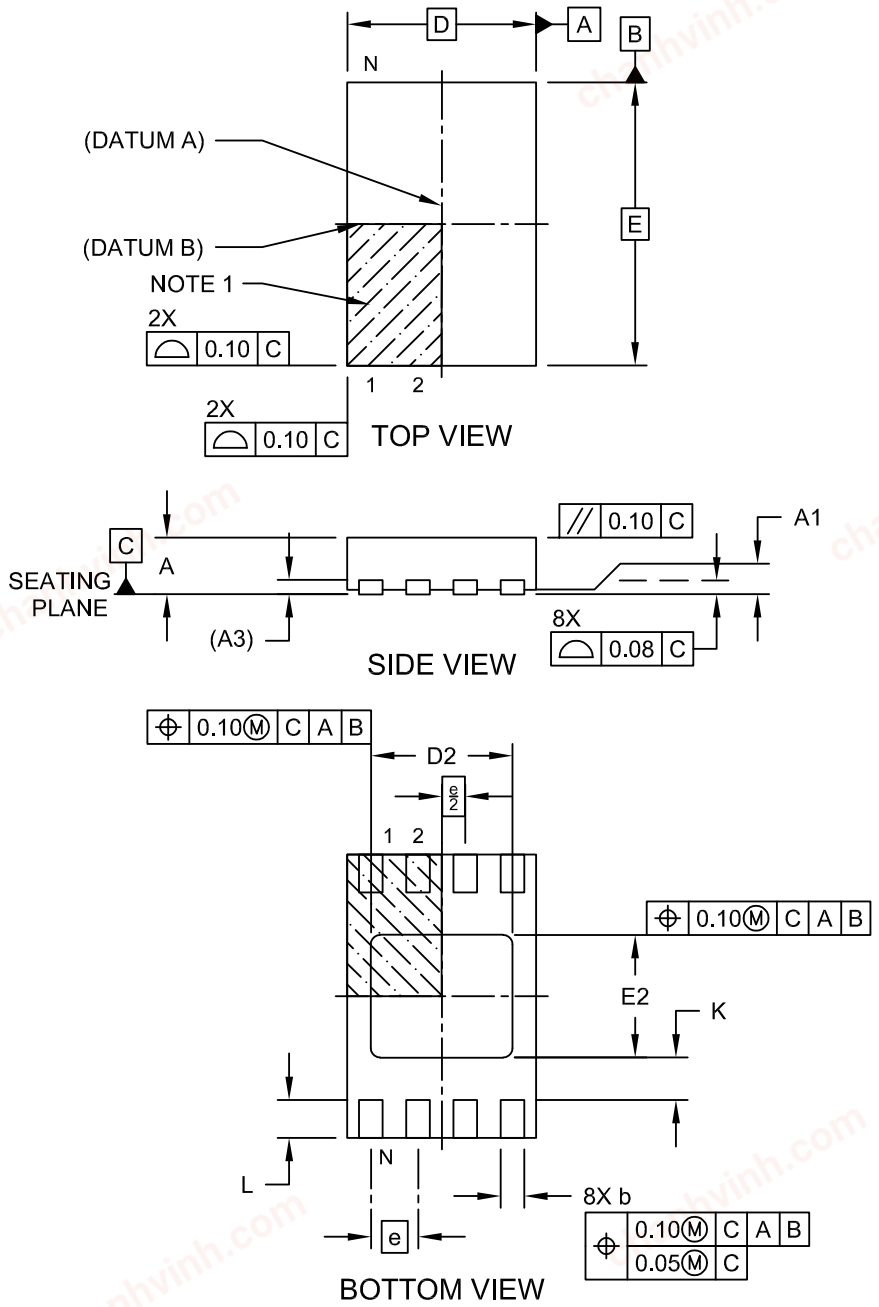
Microchip Technology Drawing C04-2086 Rev B

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8-Lead Ultra Thin Plastic Dual Flat, No Lead Package (Q4B) - 2x3 mm Body [UDFN]
Atmel Legacy Global Package Code YNZ

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



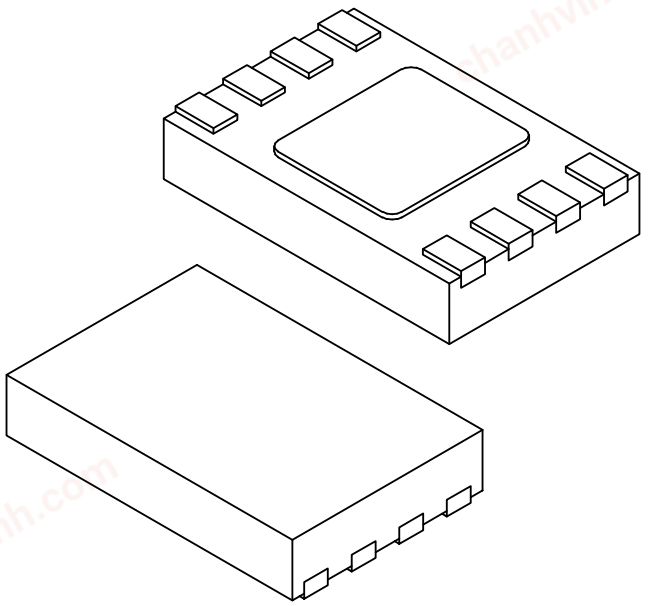
Microchip Technology Drawing C04-21355-Q4B Rev C Sheet 1 of 2

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8-Lead Ultra Thin Plastic Dual Flat, No Lead Package (Q4B) - 2x3 mm Body [UDFN]
Atmel Legacy Global Package Code YNZ

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Terminals	N		8	
Pitch	e		0.50 BSC	
Overall Height	A	0.50	0.55	0.60
Standoff	A1	0.00	0.02	0.05
Terminal Thickness	A3		0.152 REF	
Overall Length	D		2.00 BSC	
Exposed Pad Length	D2	1.40	1.50	1.60
Overall Width	E		3.00 BSC	
Exposed Pad Width	E2	1.20	1.30	1.40
Terminal Width	b	0.18	0.25	0.30
Terminal Length	L	0.25	0.35	0.45
Terminal-to-Exposed-Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

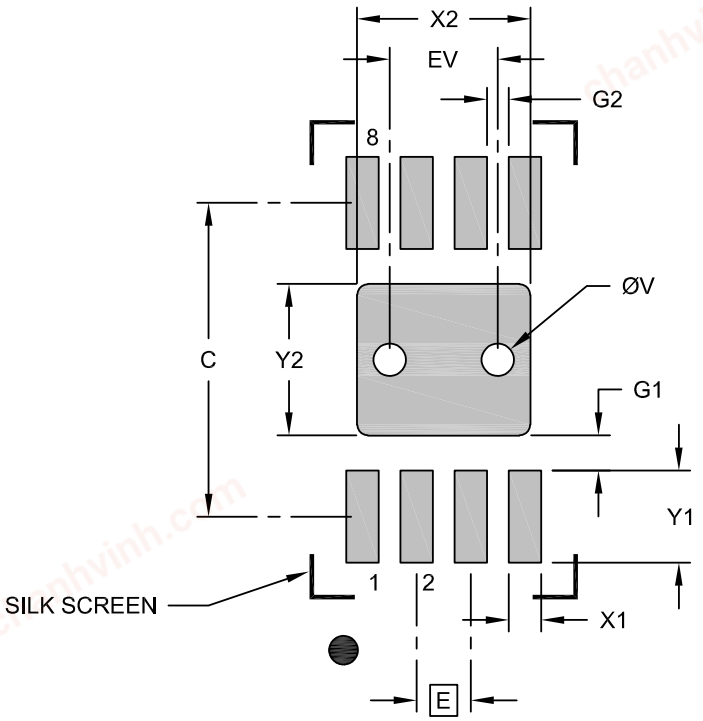
Microchip Technology Drawing C04-21355-Q4B Rev C Sheet 2 of 2

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8-Lead Ultra Thin Plastic Dual Flat, No Lead Package (Q4B) - 2x3 mm Body [UDFN]
Atmel Legacy Global Package Code YNZ

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.50 BSC	
Optional Center Pad Width	X2			1.60
Optional Center Pad Length	Y2			1.40
Contact Pad Spacing	C		2.90	
Contact Pad Width (X8)	X1			0.30
Contact Pad Length (X8)	Y1			0.85
Contact Pad to Center Pad (X8)	G1	0.33		
Contact Pad to Contact Pad (X6)	G2	0.20		
Thermal Via Diameter	V		0.30	
Thermal Via Pitch	EV		1.00	

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
2. For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process

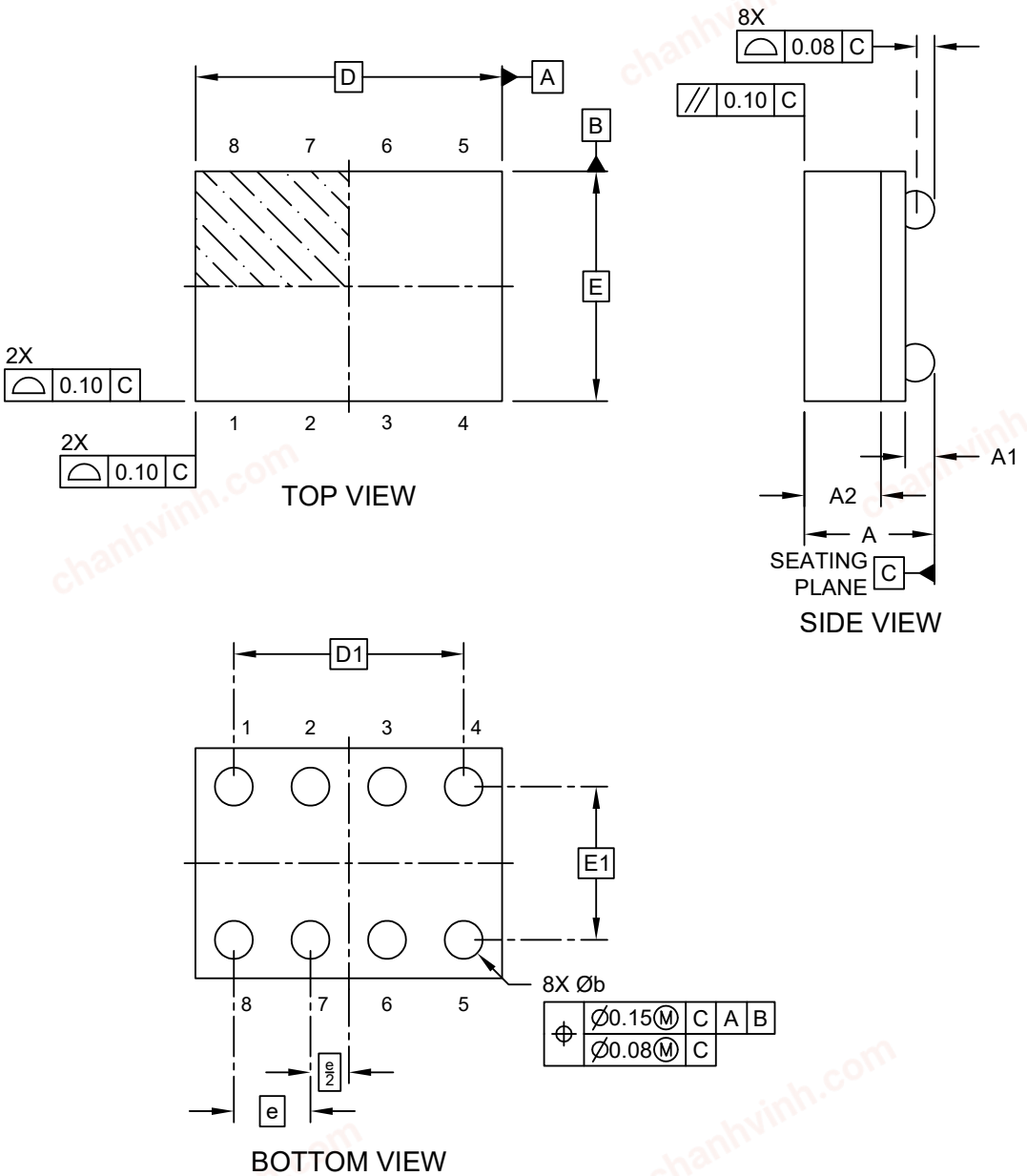
Microchip Technology Drawing C04-23355-Q4B Rev C

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8-Ball Very Thin Fine-Pitch Ball Grid Array Package (E8B) - 1.50x2.00x0.85 mm Body [VFBGA] ; Atmel Global Package Code GXU

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



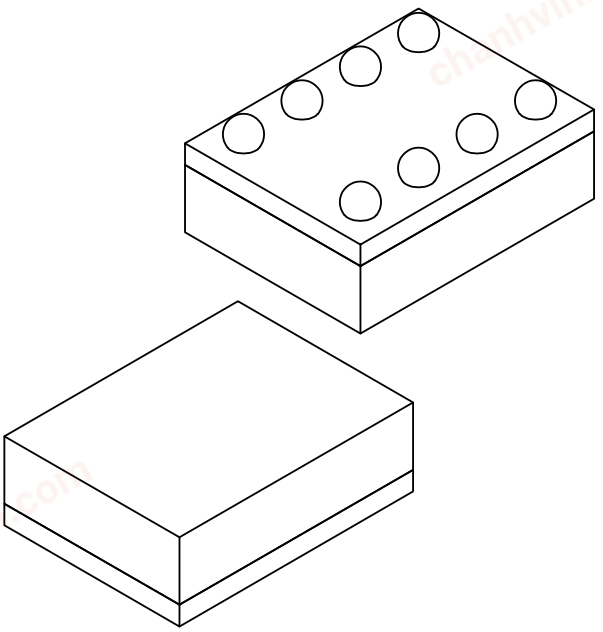
Microchip Technology Drawing C04-21198 Rev A Sheet 1 of 2

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8-Ball Very Thin Fine-Pitch Ball Grid Array Package (E8B) - 1.50x2.00x0.85 mm Body [VFBGA] ; Atmel Global Package Code GXU

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Terminals	N		8	
Pitch	e		0.50	
Overall Height	A	0.73	0.79	0.85
Ball Height	A1	0.09	0.14	0.19
Mold Thickness	A2	0.40	0.45	0.50
Overall Length	D		2.00 BSC	
Ball Array Length	D1		1.50 BSC	
Overall Width	E		1.50 BSC	
Ball Array Width	E1		1.00 BSC	
Ball Diameter	b	0.20	0.25	0.30

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.

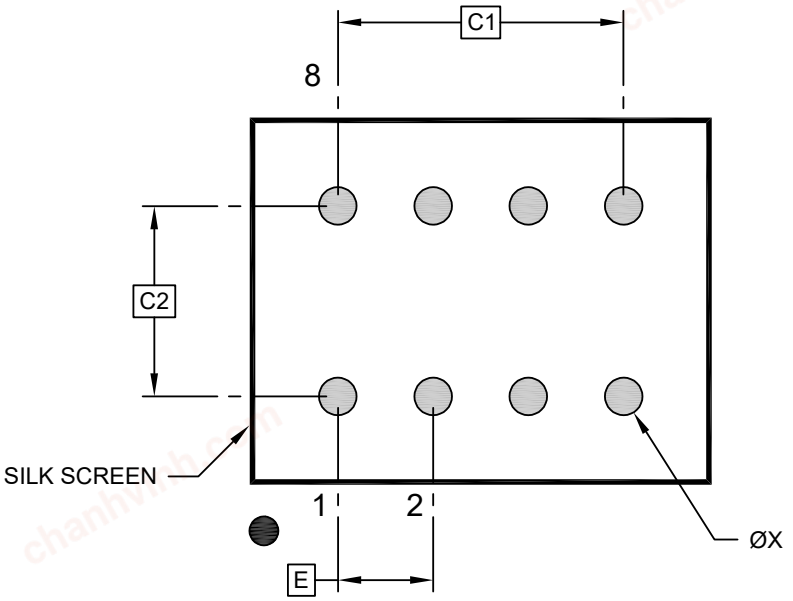
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8-Ball Very Thin Fine-Pitch Ball Grid Array Package (E8B) - 1.50x2.00x0.85 mm Body [VFBGA] ; Atmel Global Package Code GXU

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.40 BSC	
Contact Pad Spacing	C1		1.50 BSC	
Contact Pad Spacing	C2		1.00 BSC	
Contact Pad Width (X8)	X			0.20

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-23198 Rev A

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11. Revision History

Revision C (November 2024)
Corrected SOT23 package drawing reference in the Product Information System examples table to match the SOT23 NMB POD. No change to form, fit or function. Updated Date Codes table format.

Revision B (October 2023)
Removed 8-pad XDFN product offering. Replaced terminology “Master” and “Slave” with “Host” and “Client”, respectively.

Revision A (August 2018)
Updated to the Microchip template. Microchip DS20006051 replaces Atmel document 8719. Corrected t_{LOW} typo from 400 ns to 500 ns. Corrected t_{AA} typo from 550 ns to 450 ns. Updated Part Marking Information. Updated the "Software Reset" section. Added ESD rating. Removed lead finish designation. Updated trace code format in package markings. Added a figure for “System Configuration Using 2-Wire Serial EEPROMs”. Updated "Block Diagram" figure. Added POR recommendations section. Updated section content throughout for clarification. Updated the 5TS1 SOT23 and 8U3-1 VFBGA package drawings. Updated the PDIP, SOIC, TSSOP and UDFN package drawings to Microchip format.

Atmel Document 8719 Revision D (December 2016)
Part marking SOT23:

- Moved backside mark (YMXX) to front side line2
- Added @ = Country of Assembly

Atmel Document 8719 Revision C (January 2015)
Added the UDFN Expanded Quantity Option. Updated the 8X, 8MA2, 8P3, and 8U3-1 package outline drawings, the ordering information section, and the disclaimer page.

Atmel Document 8719 Revision B (July 2013)
Minor grammatical corrections. Updated Atmel logos and template.

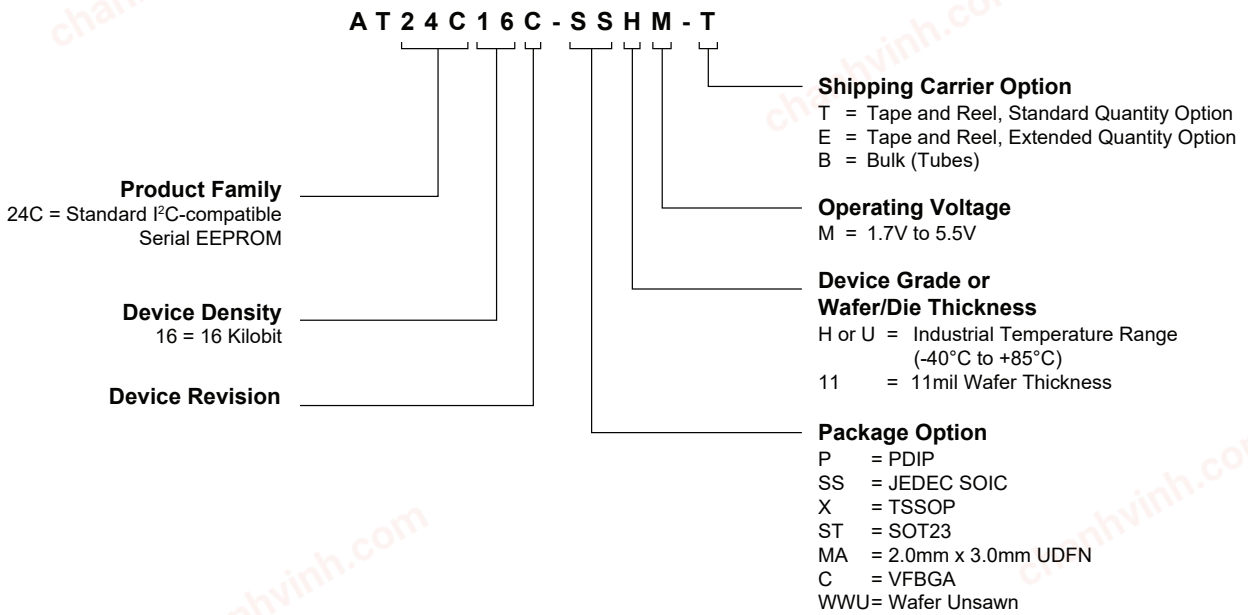
Atmel Document 8719 Revision A (September 2010)
Initial release of this document.

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12. Product Identification System

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.



Note: Refer to automotive data sheet for automotive grade ordering information.

Examples

Device	Package	Package Drawing Code	Package Option	Shipping Carrier Option	Device Grade
AT24C16C-PUM	PDIP	P	P	Bulk (Tubes)	Industrial Temperature (-40°C to +85°C)
AT24C16C-SSHM-T	SOIC	SN	SS	Tape and Reel	
AT24C16C-STUM-T	SOT-23	NMB	ST	Tape and Reel	
AT24C16C-XHM-B	TSSOP	ST	X	Bulk (Tubes)	
AT24C16C-MAHM-T	UDFN	Q4B	MA	Tape and Reel	
AT24C16C-MAHM-E	UDFN	Q4B	MA	Extended Qty. Tape and Reel	
AT24C16C-CUM-T	VFBGA	E8B	C	Tape and Reel	

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